Product Change Notification

Change Notification #: 118315-00

Change Title: Select Intel® Optane™ Memory H10 with Solid State Storage, PCN 118315-00, Label, Label Update

Date of Publication: June 16, 2021

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 16, 2021

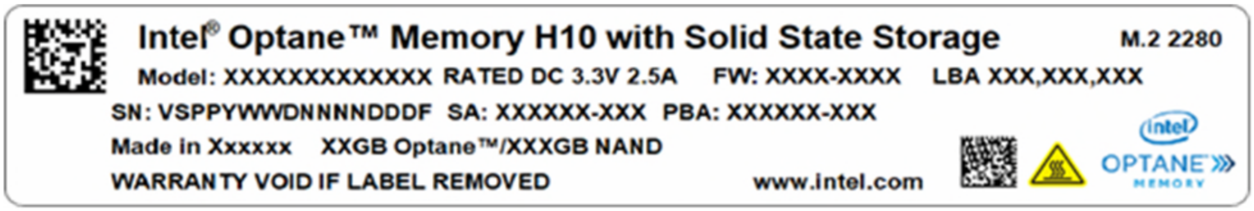
Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following changes.

- Change 1. Update Customer Label with UKCA for (MOQ1 and MOQ100) all SKUs
- Change 2. Add UKCA Package Label for (MOQ100) MM#999MJH, 999MJJ, 999MJK

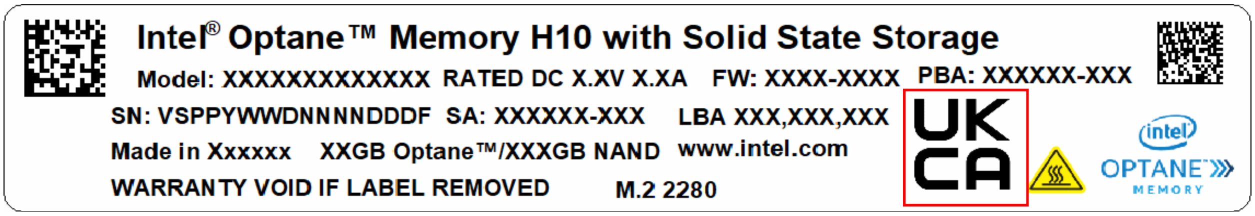
Change 1: New Customer Label (MOQ1)

Current



Intel® Optane™ Memory H10 with Solid State Storage M.2 2280
Model: XXXXXXXXXXXXX RATED DC 3.3V 2.5A FW: XXXX-XXXX LBA XXX,XXX,XXX
SN: VSPPYWWDNNNNDDDF SA: XXXXXX-XXX PBA: XXXXXX-XXX
Made in Xxxxxx XXGB Optane™/XXXGB NAND
WARRANTY VOID IF LABEL REMOVED www.intel.com

New



Intel® Optane™ Memory H10 with Solid State Storage
Model: XXXXXXXXXXXXX RATED DC X.XV X.XA FW: XXXX-XXXX PBA: XXXXXX-XXX
SN: VSPPYWWDNNNNDDDF SA: XXXXXX-XXX LBA XXX,XXX,XXX
Made in Xxxxxx XXGB Optane™/XXXGB NAND www.intel.com
WARRANTY VOID IF LABEL REMOVED M.2 2280

Change 2: New Package Label (MOQ100)

New

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the labels used in packaging. Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Optane™ Memory H10 with Solid State Storage (16GB + 256GB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic Single Pack	HBRPEKNX0101A08	999MJ9
Intel® Optane™ Memory H10 with Solid State Storage (32GB + 512GB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic Single Pack	HBRPEKNX0202A08	999MJF
Intel® Optane™ Memory H10 with Solid State Storage (32GB + 1TB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic Single Pack	HBRPEKNX0203A08	999MJG
Intel® Optane™ Memory H10 with Solid State Storage (16GB + 256GB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic 100 Pack	HBRPEKNX0101A06	999MJH
Intel® Optane™ Memory H10 with Solid State Storage (32GB + 512GB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic 100 Pack	HBRPEKNX0202A06	999MJJ
Intel® Optane™ Memory H10 with Solid State Storage (32GB + 1TB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic 100 Pack	HBRPEKNX0203A06	999MJK

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 16, 2021	00	Originally Published PCN

Product Change Notification
118315-00

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
Europe Email: eccb@intel.com
Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2021. Other names and brands may be claimed as the property of others.

3D XPoint, Axxia, Basis, Basis Peak, BlueMoon, BunnyPeople, Celeron, Centrino, Cilk, Curie, Flexpipe, Intel, the Intel logo, Intel Atom, Intel CoFluent, Intel Core, Intel. Experience What's Inside, the Intel. Experience What's Inside logo, Intel Inside, the Intel Inside logo, Intel Insider, Intel Joule, Intel RealSense, Intel SingleDriver, Intel SpeedStep, Intel Unite, Intel vPro, Intel Xeon Phi, Intel XScale, InTru, the InTru logo, the InTru Inside logo, InTru soundmark, Iris, Itanium, MCS, MMX, Optane, Ostro, Pali, Pentium, picoArray, Picochip, picoXcell, Puma, Quark, SMARTi, Soletta, Sound Mark, StarPro, Stay With It, the Engineering Stay With It logo, StreamSight, Tarari, The Journey Inside, Thunderbolt, the Thunderbolt logo, Transcede, True Key, Ultrabook, VTune, Xeon, X-GOLD, XMM, X-PMU and XPOSYS are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

Microsoft, Windows, and the Windows logo are trademarks, or registered trademarks of Microsoft Corporation in the United States and/or other countries. Java is a registered trademark of Oracle and/or its affiliates. Bluetooth is a trademark owned by its proprietor and used by Intel Corporation under license. Intel Corporation uses the Palm OS* Ready mark under license from Palm, Inc. OpenCL and the OpenCL logo are trademarks of Apple Inc. used by permission by Khronos.

Learn how to use Intel Trademarks and Brands correctly at http://www.intel.com/intel/legal/tmusage2.htm.